

# T-1 (3mm) BI-LEVEL LED INDICATOR

Part Number: L-7104MD/2ID

High Efficiency Red

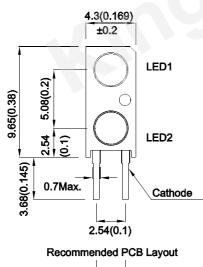
### **Features**

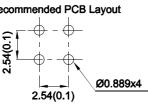
- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- · RoHS compliant.

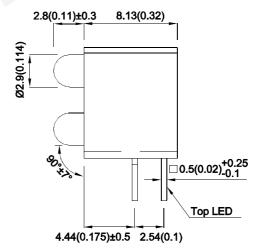
## **Description**

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

## **Package Dimensions**







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where leads emerge from the package.
   The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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## **Selection Guide**

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
1. 7404MD/0ID	High Efficiency Red (GaAsP/GaP)	Dod Diffused	12	30	40°
L-7104MD/2ID		Red Diffused	*10	*20	

### Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

# Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=10mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=10mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=10mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	1.9	2.5	V	IF=10mA
IR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

- 1. Wavelength: +/-1nm.
  2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
  4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

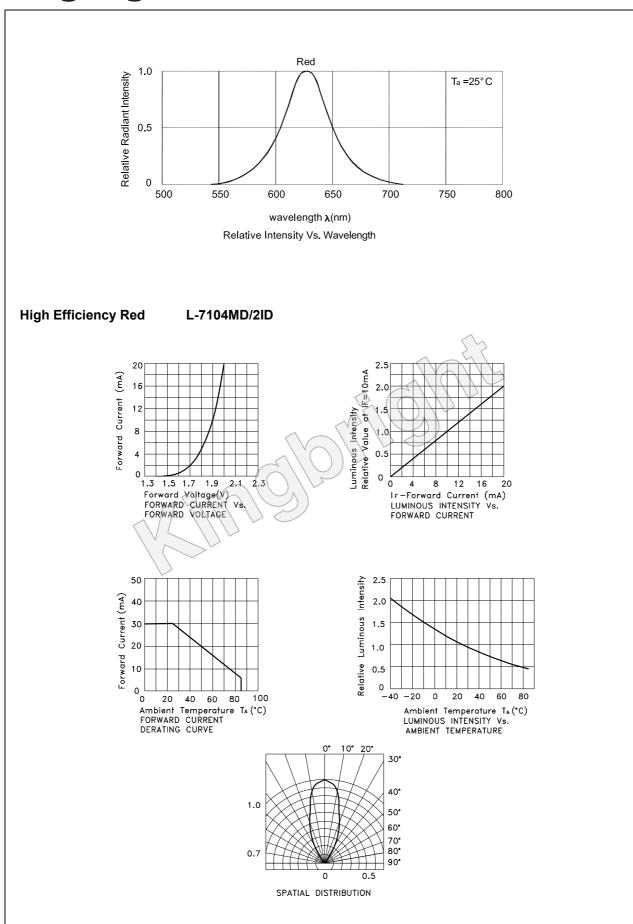
## Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
   3. 5mm below package base.

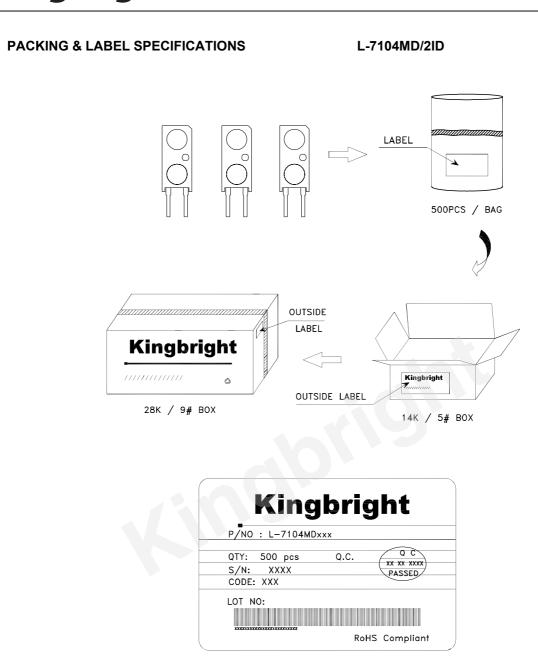
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Luminous intensity/ luminous Flux: +/-15%.
 \*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.



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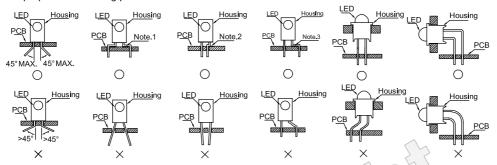
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### **PRECAUTIONS**

- 1. Storage conditions:
  - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
  - b.LEDs should be stored with temperature  $\leq$  30°C and relative humidity < 60%.
  - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 ( $\pm$ 10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



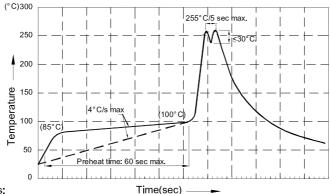
"  $\bigcirc$  " Correct mounting method " imes " Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



Notes: Time(sec) — — — 1.Recommend pre-heat temperature of 105° C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum

solder bath temperature of 260°C

2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).

- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

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